



ALPHA & OMEGA
SEMICONDUCTOR



AOL1428

N-Channel Enhancement Mode Field Effect Transistor

General Description

The AOL1428 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. This device is suitable for use as a high side switch in SMPS and general purpose applications.

-RoHS Compliant

-Halogen and Antimony Free Green Device*

Features

V_{DS} (V) = 30V

I_D = 45A (V_{GS} = 10V)

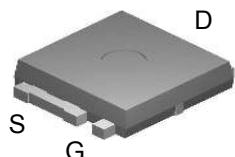
$R_{DS(ON)}$ < 9.5mΩ (V_{GS} = 10V)

$R_{DS(ON)}$ < 16mΩ (V_{GS} = 4.5V)

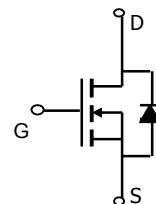
UIS Tested

R_g , C_{iss} , C_{oss} , C_{rss} Tested

Ultra SO-8™ Top View



Bottom tab
connected to
drain



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^B	I_D	49	A
$T_C=100^\circ\text{C}$		34	
Pulsed Drain Current	I_{DM}	120	
Continuous Drain Current ^H	I_{DSM}	11	A
$T_A=70^\circ\text{C}$		9	
Avalanche Current ^C	I_{AR}	30	A
Repetitive avalanche energy $L=0.3\text{mH}$ ^C	E_{AR}	135	mJ
Power Dissipation ^B	P_D	43	W
$T_C=100^\circ\text{C}$		21	
Power Dissipation ^A	P_{DSM}	2.2	W
$T_A=70^\circ\text{C}$		1.5	
Junction and Storage Temperature Range	T_J , T_{STG}	-55 to 175	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	19	25	°C/W
Maximum Junction-to-Ambient ^A		45	55	°C/W
Maximum Junction-to-Case ^C	$R_{\theta JC}$	2.5	3.5	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
STATIC PARAMETERS							
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}, V_{GS}=0\text{V}$		$T_J=55^\circ\text{C}$	1	μA	
					5		
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			0.1	μA	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	1.9	2.5	V	
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	120			A	
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$		$T_J=125^\circ\text{C}$	7.7	9.5	$\text{m}\Omega$
					11.0		
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=20\text{A}$		40		S	
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.74	1.0	V	
I_s	Maximum Body-Diode Continuous Current				46	A	
DYNAMIC PARAMETERS							
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		1000		pF	
C_{oss}	Output Capacitance			340		pF	
C_{rss}	Reverse Transfer Capacitance			100		pF	
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		1.3		Ω	
SWITCHING PARAMETERS							
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=20\text{A}$		18		nC	
$Q_g(4.5\text{V})$	Total Gate Charge			8.5		nC	
Q_{gs}	Gate Source Charge			3.1		nC	
Q_{gd}	Gate Drain Charge			4.8		nC	
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=0.75\Omega, R_{\text{GEN}}=3\Omega$		5.6		ns	
t_r	Turn-On Rise Time			5.5		ns	
$t_{\text{D(off)}}$	Turn-Off Delay Time			18.5		ns	
t_f	Turn-Off Fall Time			5		ns	
t_{rr}	Body Diode Reverse Recovery Time	$I_F=20\text{A}, dI/dt=100\text{A}/\mu\text{s}$		29		ns	
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=20\text{A}, dI/dt=100\text{A}/\mu\text{s}$		24		nC	

A: The value of $R_{\theta_{JA}}$ is measured with the device in a still air environment with $T_A=25^\circ\text{C}$.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=175^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=175^\circ\text{C}$.

D. The $R_{\theta_{JA}}$ is the sum of the thermal impedance from junction to case $R_{\theta_{JC}}$ and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using $<300\ \mu\text{s}$ pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=175^\circ\text{C}$.

G. These tests are performed with the device mounted on 1 in. 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

H. Surface mounted on a 1 in 2 FR-4 board with 2oz. Copper.

* This device is guaranteed green after date code 8P11 (June 1ST 2008)

Rev3: Jul 2008

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

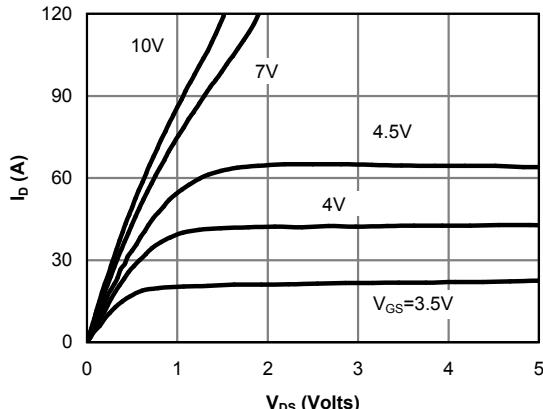


Figure 1: On-Region Characteristics

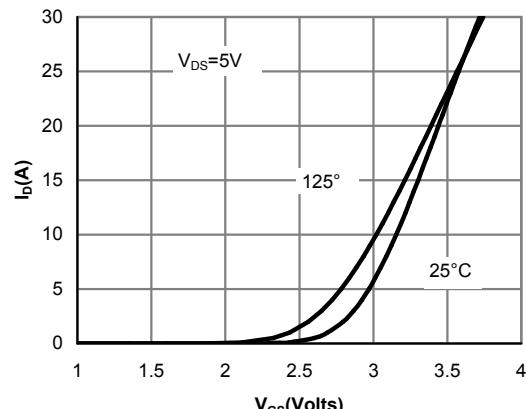


Figure 2: Transfer Characteristics

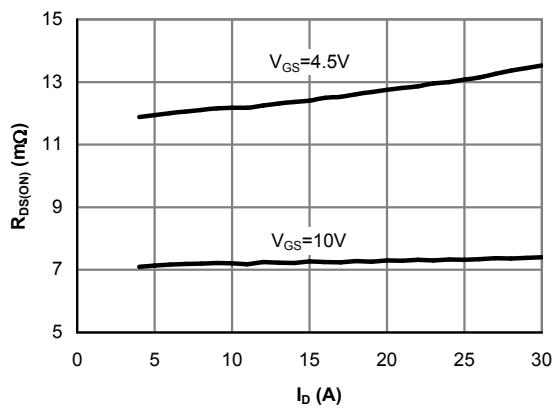


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

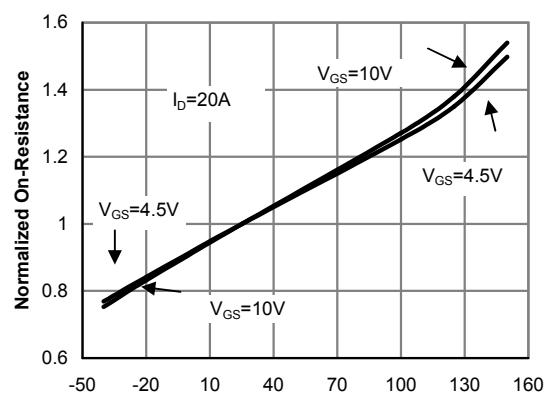


Figure 4: On-Resistance vs. Junction Temperature

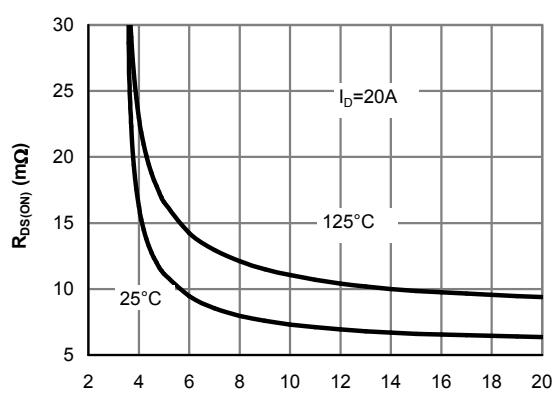


Figure 5: On-Resistance vs. Gate-Source Voltage

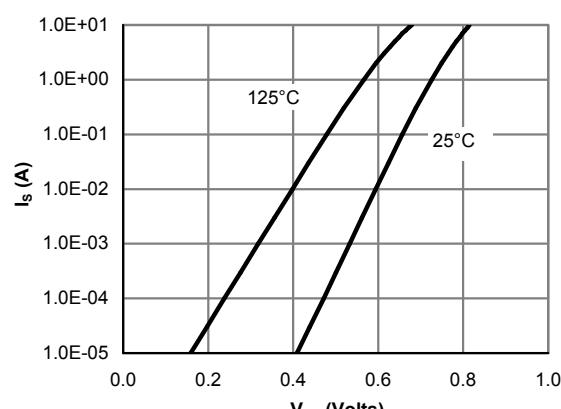


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

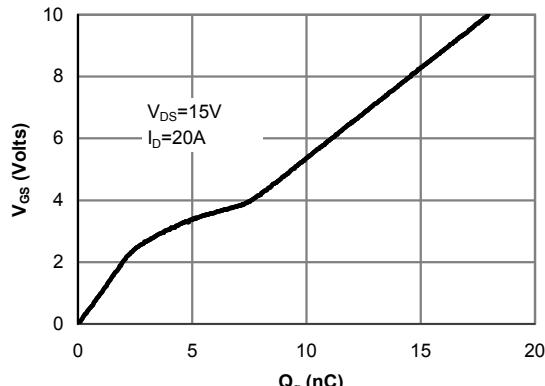


Figure 7: Gate-Charge Characteristics

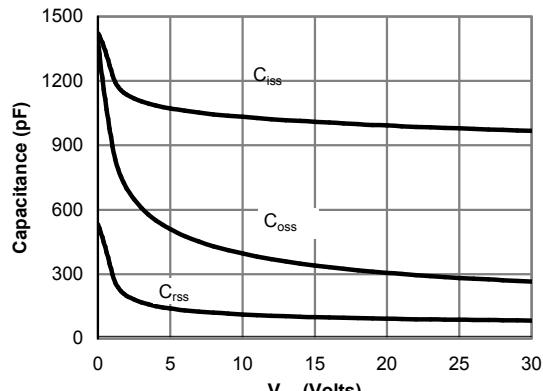


Figure 8: Capacitance Characteristics

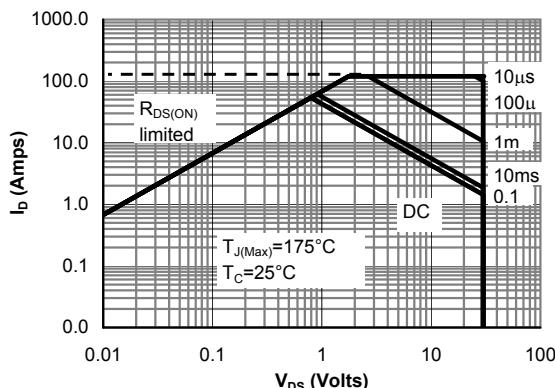


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

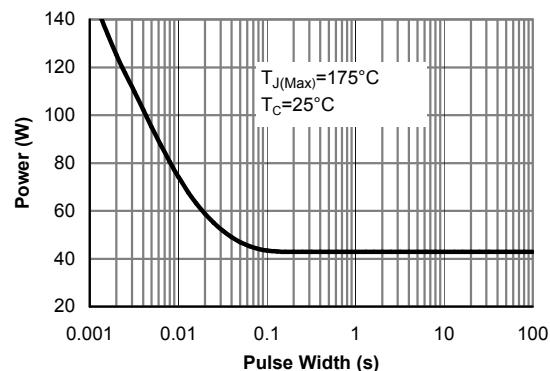


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

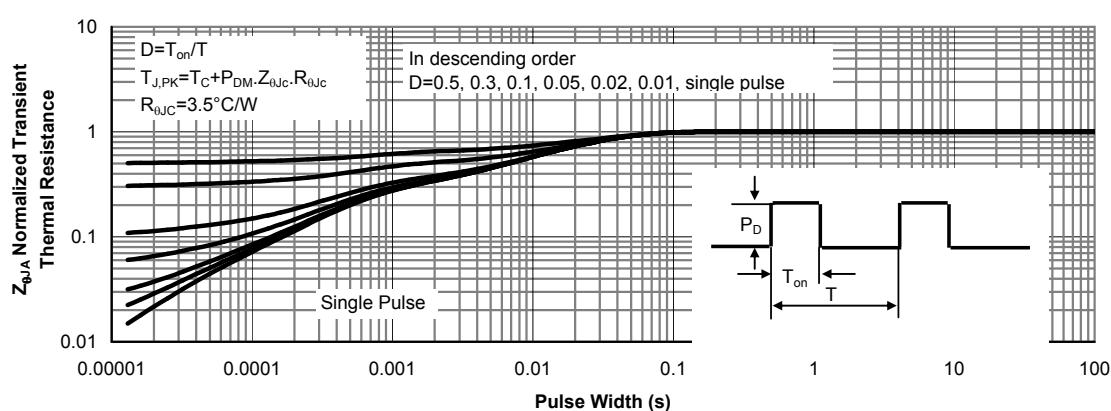


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

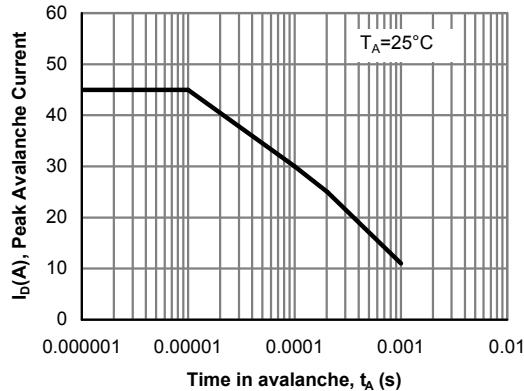


Figure 12: Single Pulse Avalanche capability

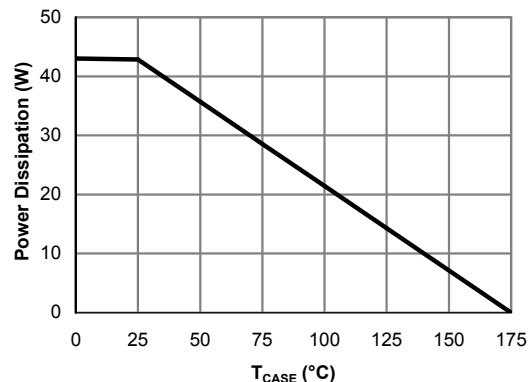


Figure 13: Power De-rating (Note B)

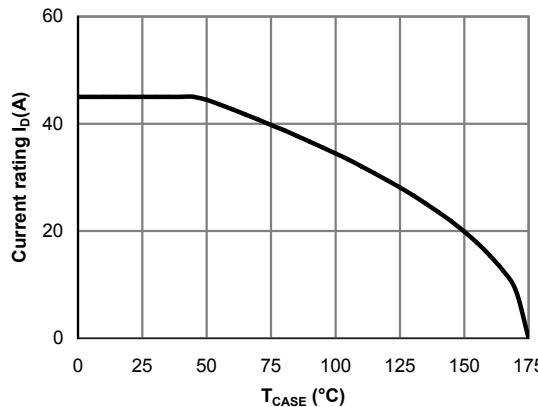


Figure 14: Current De-rating (Note B)

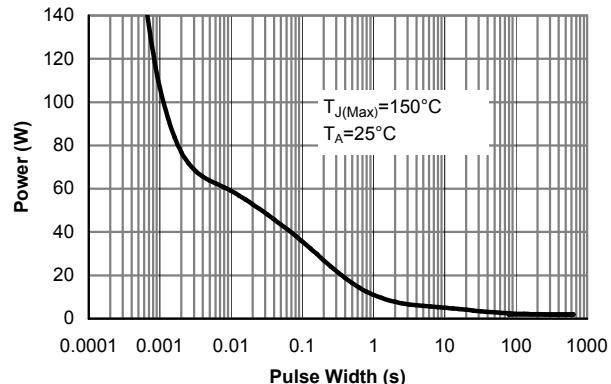


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note G)

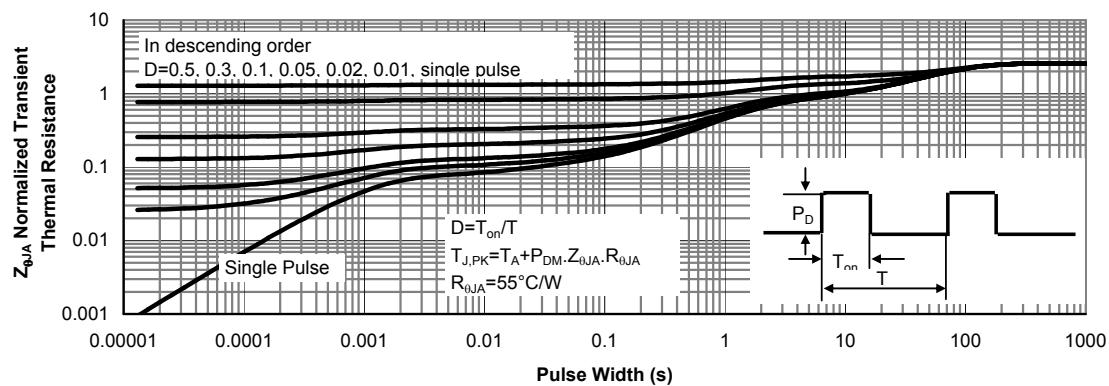
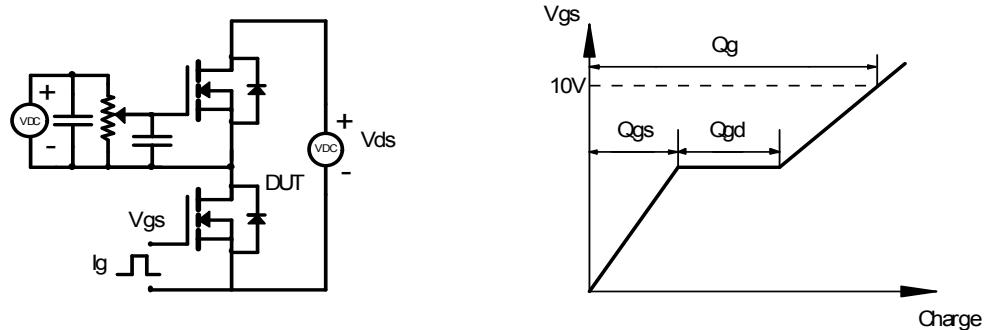
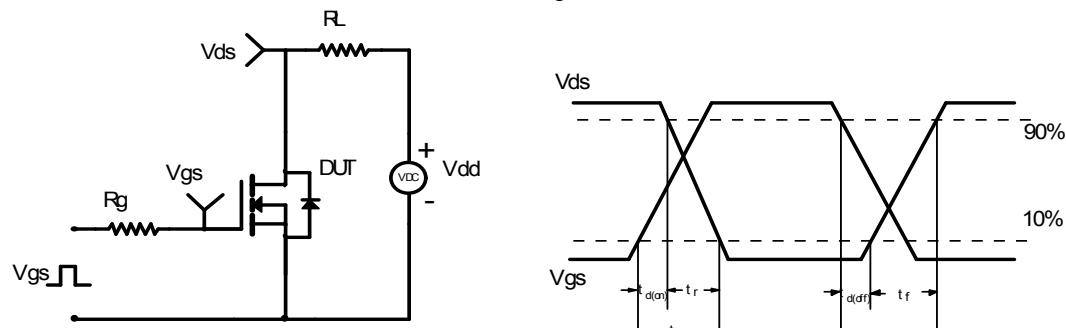


Figure 16: Normalized Maximum Transient Thermal Impedance (Note G)

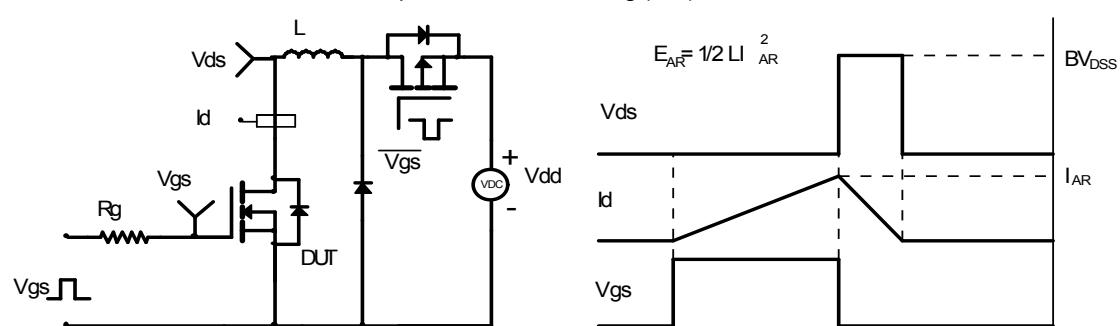
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

